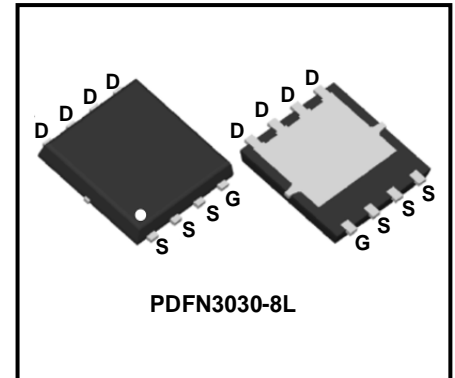


## 65V N-Channel Enhancement Mode Power MOSFET

### Description

WMQ048NV6LG2 uses Wayon's 2<sup>nd</sup> generation power trench MOSFET technology that has been especially tailored to minimize the on-state resistance and yet maintain superior switching performance. This device is well suited for high efficiency fast switching applications

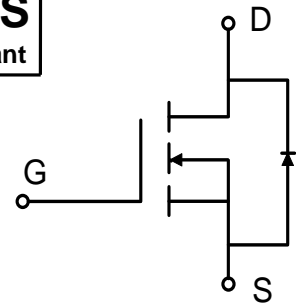


### Features

- $V_{DS} = 65V$ ,  $I_D = 60A$   
 $R_{DS(on)} < 5.1 \text{ m}\Omega @ V_{GS} = 10V$   
 $R_{DS(on)} < 7.6\text{m}\Omega @ V_{GS} = 4.5V$
- Low  $R_{DS(ON)}$
- High Speed Power Switching
- Low Gate Charge
- 100% EAS Guaranteed

### Applications

- Synchronous Rectification in SMPS
- Hard Switching and High Speed Circuit
- DC/DC Converter



### Absolute Maximum Ratings

Parameter		Symbol	Value	Unit
Drain-Source Voltage		$V_{DS}$	65	V
Gate-Source Voltage		$V_{GS}$	$\pm 20$	V
Continuous Drain Current@10V <sup>1</sup>	$T_C = 25^\circ\text{C}$	$I_D$	60	A
	$T_C = 100^\circ\text{C}$		37	
Pulsed Drain Current <sup>2</sup>		$I_{DM}$	110	A
Single Pulse Avalanche Energy <sup>3</sup>		<b>EAS</b>	100	mJ
Avalanche Current		$I_{AS}$	20	A
Total Power Dissipation <sup>4</sup>	$T_C = 25^\circ\text{C}$	$P_D$	75	W
	$T_C = 100^\circ\text{C}$		31	
Operating Junction and Storage Temperature Range		$T_J, T_{STG}$	-55 to +150	$^\circ\text{C}$

### Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal Resistance from Junction-to-Ambient <sup>1</sup>	$R_{\theta JA}$	52	$^\circ\text{C/W}$
Thermal Resistance from Junction-to-Case <sup>1</sup>	$R_{\theta JC}$	2.8	$^\circ\text{C/W}$

**Electrical Characteristics**  $T_c = 25^\circ\text{C}$ , unless otherwise noted

Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit	
<b>Static Characteristics</b>							
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = 250\mu A$	65	-	-	V	
Gate-body Leakage current	$I_{GSS}$	$V_{DS} = 0V, V_{GS} = \pm 20V$	-	-	$\pm 100$	nA	
Zero Gate Voltage Drain Current	$T_J=25^\circ\text{C}$	$I_{DSS}$	$V_{DS} = 60V, V_{GS} = 0V$	-	-	1	$\mu A$
	$T_J=55^\circ\text{C}$			-	-	5	
Gate-Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\mu A$	1.0	1.6	2.4	V	
Drain-Source On-Resistance <sup>2</sup>	$R_{DS(on)}$	$V_{GS} = 10V, I_D = 20A$	-	4.4	5.1	m $\Omega$	
		$V_{GS} = 4.5V, I_D = 10A$	-	6.2	7.6		
Forward Transconductance	$g_{fs}$	$V_{DS} = 5V, I_D = 20A$	-	58	-	S	
<b>Dynamic Characteristics</b>							
Input Capacitance	$C_{iss}$	$V_{DS} = 30V, V_{GS} = 0V, f = 1\text{MHz}$	-	1995	-	pF	
Output Capacitance	$C_{oss}$		-	785	-		
Reverse Transfer Capacitance	$C_{rss}$		-	51	-		
<b>Switching Characteristics</b>							
Gate Resistance	$R_g$	$V_{DS} = 0V, V_{GS} = 0V, f = 1\text{MHz}$	-	1.4	-	$\Omega$	
Total Gate Charge	$Q_g$	$V_{GS} = 4.5V, V_{DS} = 30V, I_D = 20A$	-	24.9	-	nC	
Total Gate Charge	$Q_g$	$V_{GS} = 10V, V_{DS} = 30V, I_D = 20A$	-	40	-		
Gate-Source Charge	$Q_{gs}$		-	5.9	-		
Gate-Drain Charge	$Q_{gd}$		-	10.6	-		
Turn-On Delay Time	$t_{d(on)}$	$V_{GS} = 10V, V_{DS} = 30V, I_D = 20A$ $R_G = 10\Omega,$	-	9.6	-	nS	
Rise Time	$t_r$		-	8.1	-		
Turn-Off Delay Time	$t_{d(off)}$		-	32	-		
Fall Time	$t_f$		-	9.5	-		
<b>Drain-Source Body Diode Characteristics</b>							
Diode Forward Voltage <sup>2</sup>	$V_{SD}$	$I_S = 1A, V_{GS} = 0V$	-	-	1	V	
Continuous Source Current <sup>1,5</sup>	$I_S$	$V_G = V_D = 0V$ , Force Current	-	-	60	A	
Body Diode Reverse Recovery Time	$t_{rr}$	$I_F = 20A, di/dt = 400A/\mu s$	-	28	-	nS	
Body Diode Reverse Recovery Charge	$Q_{rr}$		-	65	-	nC	

Note :

1. The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
2. The data tested by pulsed, pulse width  $\leq 300\mu s$ , duty cycle  $\leq 2\%$
3. The EAS data shows Max. rating. The test condition is  $V_{DD} = 25V, V_{GS} = 10V, L = 0.5mH, I_{AS} = 20A$
4. The power dissipation is limited by 150°C junction temperature
5. The data is theoretically the same as  $I_D$  and  $I_{DM}$ , in real applications, should be limited by total power dissipation.

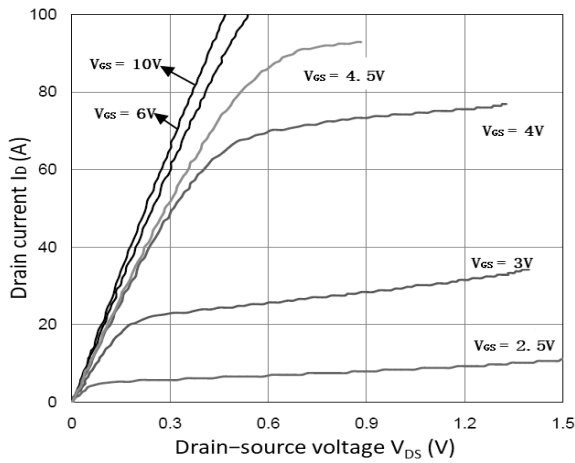


Figure 1. Output Characteristics

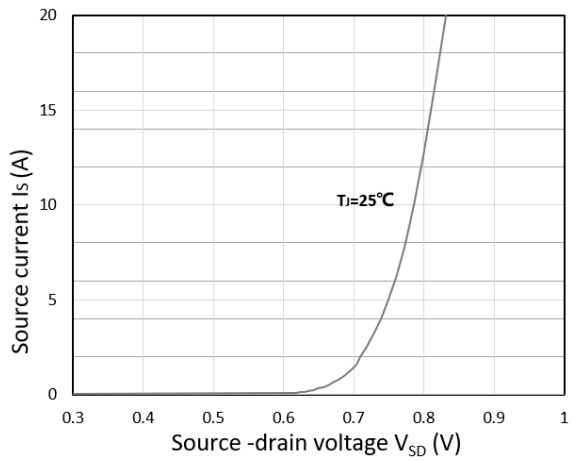


Figure 2. Forward Characteristics of Reverse

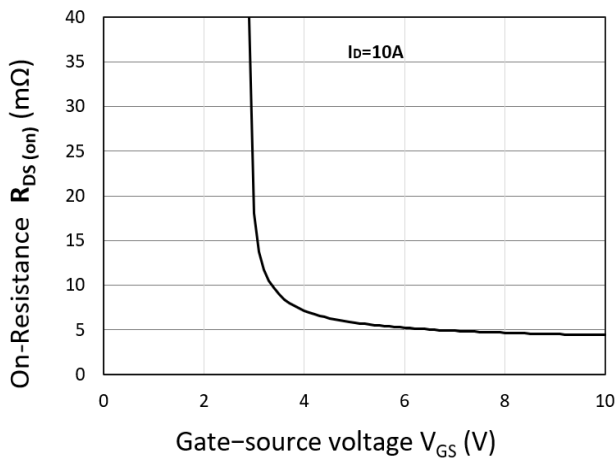


Figure 3.  $R_{DS(ON)}$  vs.  $V_{GS}$

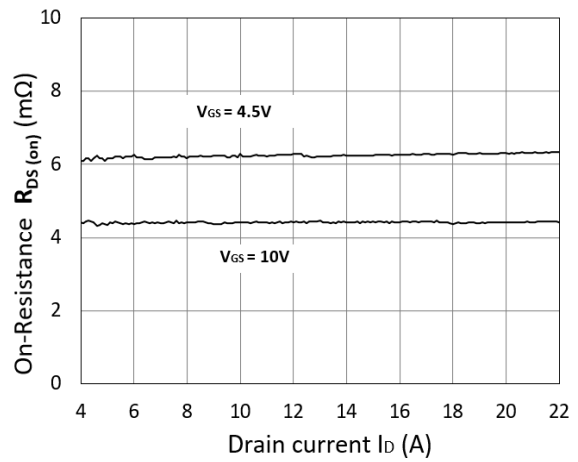


Figure 4.  $R_{DS(ON)}$  vs.  $I_D$

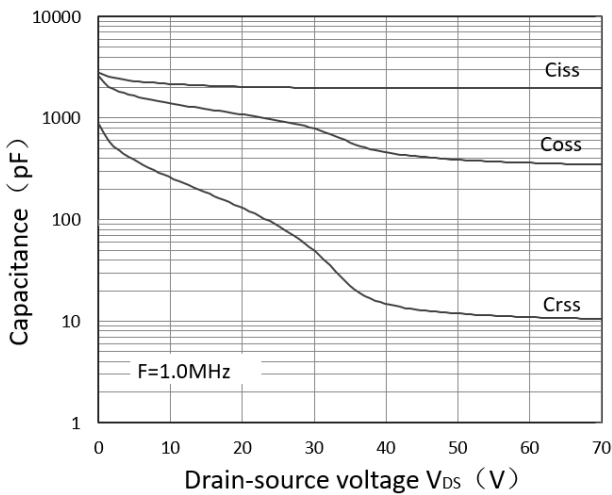


Figure 5. Capacitance Characteristics

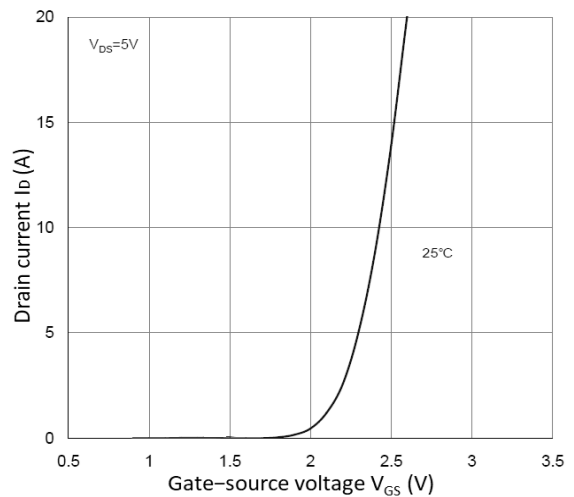


Figure 6. Transfer Characteristics

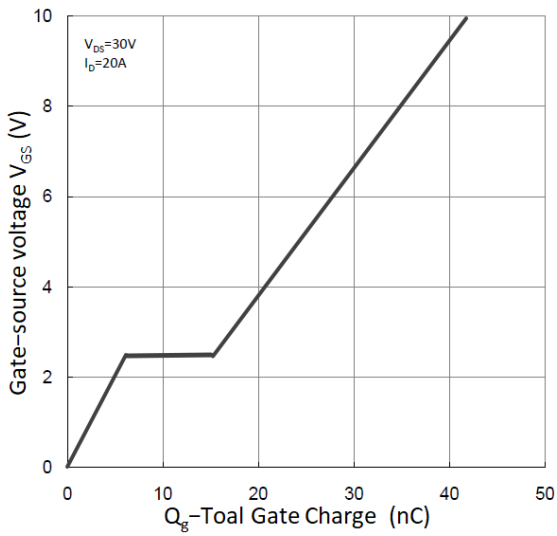


Figure 7. Gate Charge Characteristics

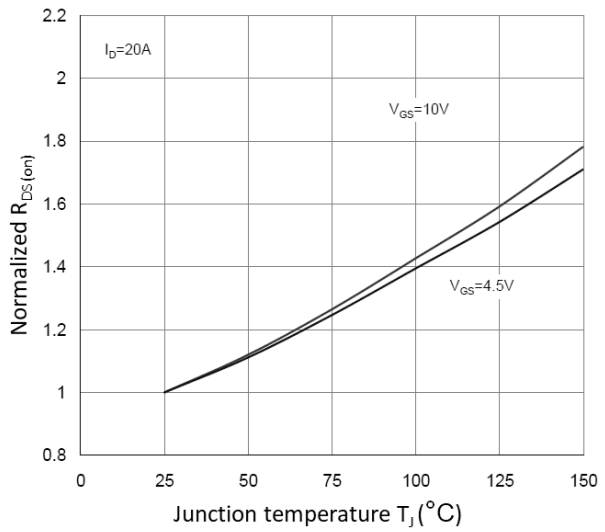


Figure 8. Normalized  $R_{DS(on)}$  vs.  $T_J$

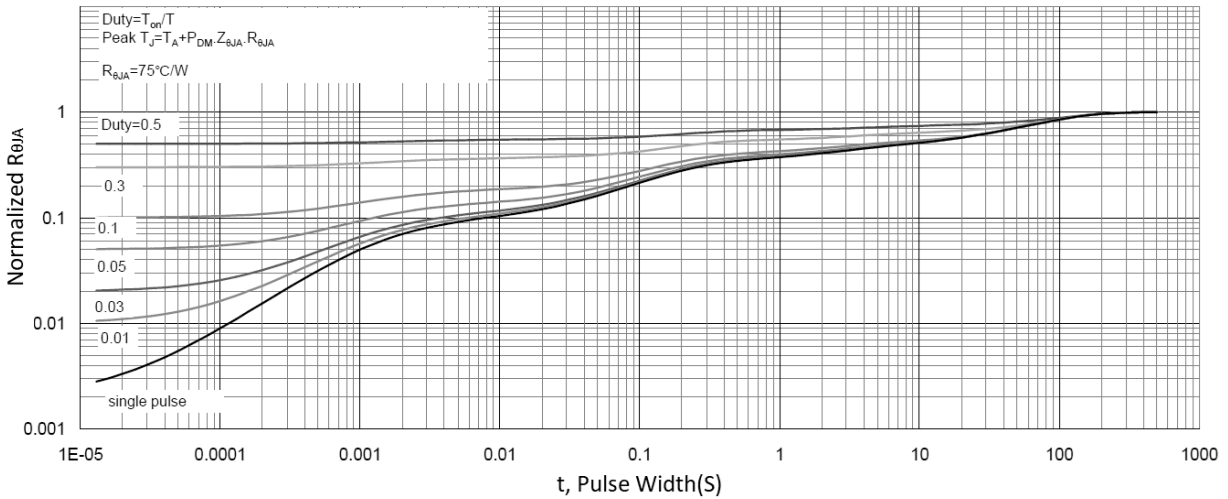


Figure 9. Normalized Maximum Transient Thermal Impedance

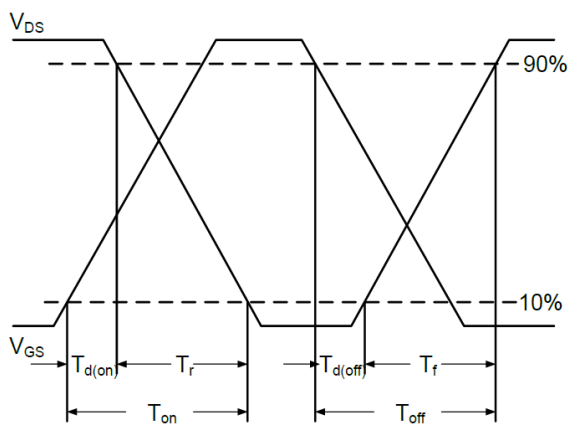


Figure 10. Switching Time Waveform

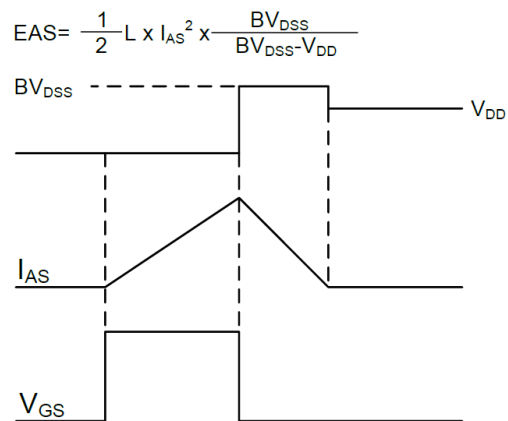
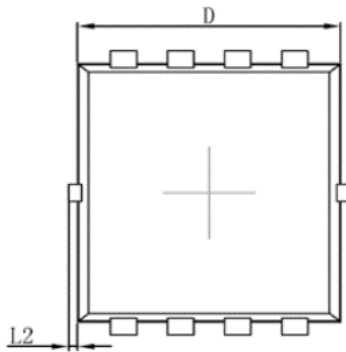
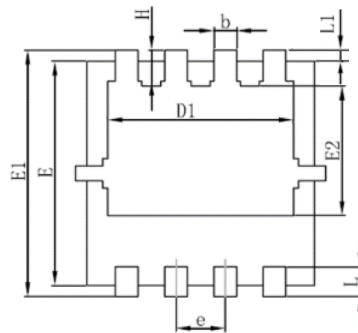


Figure 11. Unclamped Inductive Switching Waveform

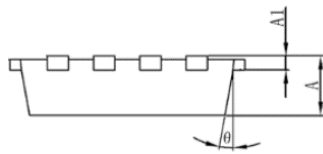
Mechanical Dimensions for PDFN3030-8L



Top View



Bottom View



Side View

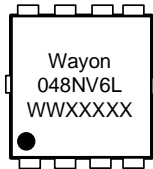
COMMON DIMENSIONS

SYMBOL	MM	
	MIN	MAX
A	0.70	0.85
A1	0.10	0.25
D	2.90	3.25
D1	2.25	2.65
E	2.90	3.20
E1	3.10	3.45
E2	1.54	1.98
b	0.20	0.40
e	0.60	0.70
L	0.30	0.50
L1	0.13BSC	
L2	0.00	0.15
H	0.20	0.65
$\theta$	0°	14°

## Ordering Information

Part	Package	Marking	Packing method
WMQ048NV6LG2	PDFN3030-8L	048NV6L	Tape and Reel

## Marking Information



048NV6L = Device code  
 WWXXXXX= Date code


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